



## Product Change Notification: MFOL-03MQJR414

**Date:**

18-Oct-2025

**Product Category:**

Special Purpose Analog to Digital Converters

**Notification Subject:**

CCB 7375 Final Notice: Qualification of MMT as a new assembly site for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers (CPN) and QMI519 as a new die attach material for TC7106, TC7106A, TC7107, TC7107A, TC7109, TC7109A, TC7116, TC7116A, TC7117, TC7117A, TC7126, TC7126A and TC7129 device families available in 44L MQFP (10x10x2mm) package.

**Affected CPNs:**

[\*\*MFOL-03MQJR414\\_Affected\\_CPN\\_10182025.pdf\*\*](#)  
[\*\*MFOL-03MQJR414\\_Affected\\_CPN\\_10182025.csv\*\*](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of MMT as a new assembly site for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers (CPN) and QMI519 as a new die attach material for TC7106, TC7106A, TC7107, TC7107A, TC7109, TC7109A, TC7116, TC7116A, TC7117, TC7117A, TC7126, TC7126A and TC7129 device families available in 44L MQFP (10x10x2mm) package.

**Pre and Post Summary Changes:**

*\* Applies only for TC7126CKW, TC7126ACKW, TC7126CKW713 and TC7126ACKW713 catalog part numbers.*

	Pre Change	Post Change
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<b>Assembly Site</b>	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)
<b>Wire Material</b>	Au	Au	Au
<b>Die Attach Material</b>	3230 (PFAS)	3230 (PFAS)	<b>QMI519 (PFAS-free)</b>
<b>Molding Compound Material</b>	G700M	G700M	<b>G600V</b>
<b>Lead-Frame Material</b>	C7025	C7025	C7025
<b>Lead-Frame Paddle Size</b>	244x244 mils	244x244 mils	<b>275x275 mils</b>
<b>DAP Surface Prep</b>	Ag Spot Plated	Ag Spot Plated	<b>Bare Cu</b>
<b>Lead- Frame Design</b>	See pre and post change for comparison.		

\* Applies for remaining affected CPNs

	<b>Pre Change</b>		<b>Post Change</b>	
<b>Assembly Site</b>	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (Branch) (MMT)
<b>Wire Material</b>	Au	Au	Au	Au
<b>Die Attach Material</b>	3230 (PFAS)	3280 (PFAS)	3230 (PFAS)	<b>QMI519 (PFAS-free)</b>
<b>Molding Compound Material</b>	G700M	G600V	G700M	G600V
<b>Lead-Frame Material</b>	C7025	C7025	C7025	C7025
<b>DAP Surface Prep</b>	Ag Spot Plated	Ag Spot Plated	Ag Spot Plated	<b>Bare Cu</b>
<b>Lead- Frame Design</b>	See pre and post change for comparison.			

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance and manufacturability by qualifying MMT as a new assembly site and QMI519 as a new die attach material.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 10 November 2025 (date code: 2546)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	March 2025					> October 2025					November 2025				
	10	11	12	13	14		40	41	42	43	44	45	46	47	48
Work Week															
Initial PCN Issue Date		x													
Qual Report Availability									x						
Final PCN Issue Date									x						
Estimated Implementation Date												x			

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_{Qual\_Report}.

**Revision History:** March 10, 2025: Issued final notification.

March 17, 2025: Re-issued the PCN notification to update the revision history stating from final notification to initial notification.

October 18, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 10, 2025. Updated the reason for change to include QM519 die attach material and included in Pre and Post change table that QMI519 is a PFAS-free material. Attached the PFAS Elimination and Die Attach Elimination file.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance

regarding the material content of the applicable product.

**Attachments:**

[\*\*PCN\\_MFOL-03MQJR414\\_Pre and Post Change\\_Summary.pdf\*\*](#)

[\*\*PCN\\_MFOL-03MQJR414 Qual Report.pdf\*\*](#)

[\*\*PFAS Elimination and Die Attach\\_Explanation.pdf\*\*](#)

Please contact your local [\*\*Microchip sales office\*\*](#) with questions or concerns regarding this notification.

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